



德高化成 TECORÉ SYNCHEM

TECHNICAL DATA SHEET

Version 1.0
Revision Date 2015/11

High-Performance Transparent Epoxy Encapsulation Material 高性能透明环氧树脂封装材料 TECORÉ® TC-8000

TECORÉ® TC-8000 is a high-performance transparent solid epoxy specifically developed for LED encapsulation.

TC-8000 is a monocomponent epoxy. Superior adhesion performance, transmittance and stability at high temperature helps achieve best package performance and long life.

德高化成TECORÉ® TC-8000 是用于LED芯片、LED显示灯等材料封装的高性能透明环氧树脂。产品为单组分，优异的粘接性、透光性和良好的高温黄变效果使得该产品起到最佳的封装效果及长寿命。

推荐使用TECORÉ® C60和W80清模和润模橡胶对半导体塑封模具进行清洁和维护。
(请向德高化成当地的销售代表处和经销商索取TECORÉ® 清模橡胶产品的TDS。)

1. TYPICAL PROPERTIES 主要性能

Item 项目	Unit 单位	Value 特征值	
Appearance 外观	-	White, Cylindrical Tablet 白色,圆柱颗粒	
Specific Gravity 比重	-	1.24	
Spiral Flow 流动长度	cm	80-200	
Gel Time 凝胶化时间	sec	18-26	
Hardness 硬度	Shore D	86	
Glass Transition Temperature 玻璃化温度	°C	125	
Coefficient of Linear Thermal Expansion 线性膨胀系数	Alpha 1	ppm/°C	78
	Alpha 2	ppm/°C	260
Flexural Strength 弹性强度	N/mm ²	110	
Flexural Modulus 弹性模量	N/mm ²	2900	
Water Absorption 吸水率(25°C 24hrs)	wt%	0.2	
Transmittance at 450 nm	%	88	
Refractive Index at 589.3 nm	-	1.56	

THE SMART CHEMICAL™

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2. HOW TO USE 使用方法

Recommended Molding Parameters 推荐的塑封参数

Molding Condition 塑封条件	Unit 单位	Parameter 参数
Preheating Time 预热温度	°C	60-80
Mold Temperature 模具温度	°C	150-160
Transfer Pressure 转进压力	kgf/cm ²	30-80
Transfer Time 转进时间	sec	20-50
Curing Time 固化时间	min	4-5
Post Molding Cure Time 后固化时间	hour	4

***Notes: Please ask the local sales office for help, in case of problems during molding process.**

如果遇到封装工程的问题，请与德高化成当地代表处或经销商联络以取得帮助。

3. PACKING 包装方式

The epoxy molding compound is sealed with aluminum laminated bags, in quantity of 2kg (for diameter 35mm).

环氧树脂塑封料成品用铝箔袋密封，每箱2kg。

4. STORAGE 储存注意事项

The users are suggested to store and use the products by following the recommended conditions as below 建议顾客按照如下推荐的条件存储和使用本产品：

4.1 Please pay attention to keep the product moisture-free, and the humidity may cause curing failures or deterioration of epoxy molding compounds.

注意保证产品一直处于干燥的环境中，湿气可能会导致产品固化问题或变质。

4.2 Keep at temperature not exceeding 5°C, and thaw 18~24 hours with sealed package before using until product temperature reaches room temperature. And the cold surface will absorb humidity in the air.

5°C以下低温存储，使用时保证密封状态回温18~24小时，直至达到室温。产品表面低于室温会导致空气中的水汽凝结并聚集在环氧树脂塑封料表面。

4.3 Keep away from sources of heat, such as molding dies, lead-frame preheating panels. The unlimited heat absorption will cause invalidations of epoxy molding compounds.

远离塑封模具、预热台等热源。不加控制的受热会导致环氧塑封料提早过期失效。

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4.4 Shelf life: If stored under proper conditions, product retains its performance and properties for 6 months from manufactured day.

储存期限：在适宜的储存条件下储存时间均为6个月。

Note: Above the technical information and data should be considered representative or typical only and should not be used for specification purposes.

注意：以上所列技术信息仅为代表性数据，不能代替技术规格书。